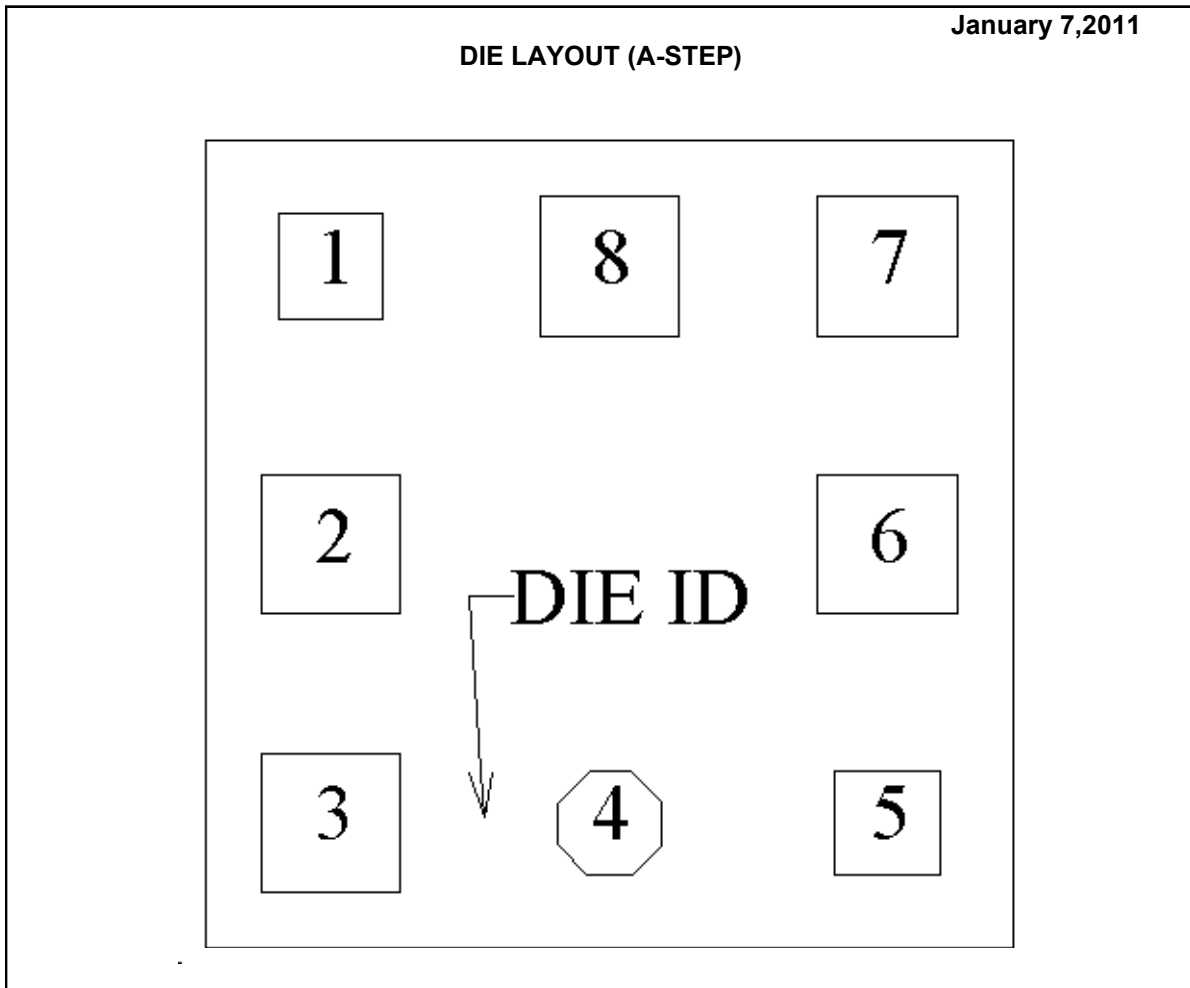


DP83213 MWF



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DP83213A	Bond Pad Opening Size (min)	95µm x 95µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	POLYIMIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	737µm x 737µm 29.0mils x 29.0mils	Back Side Connection	N/A
Thickness	304.8µm Nominal		
Min Pitch	254µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE	
		X	Y	X	Y
Pad 1	1	-254	254	95	x 95
Pad 2	2	-254	0	127	x 127
Pad 3	3	-254	-254	127	x 127
Pad 4	4	0	-254	95	x 95
Pad 5	5	254	-254	95	x 95
Pad 6	6	254	0	127	x 127
Pad 7	7	254	254	127	x 127
Pad 8	8	0	254	127	x 127

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